

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Jong-hyon Ahn  
Filing Date: Herewith  
Title: METAL INTERCONNECT LAYER OF SEMICONDUCTOR DEVICE  
AND METHOD FOR FORMING A METAL INTERCONNECT LAYER

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June 12, 2001  
Date

Vanessa Marakas  
Vanessa Marakas

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BOX PATENT APPLICATION  
Assistant Commissioner for Patents  
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Sir:

Prior to prosecution on the merits, please amend the above-identified application as follows:

In the Claims

Please amend the claims as follows:

10. (Amended) A metal interconnect layer for a semiconductor device, comprising:  
a first upper portion having a first width;  
a second middle portion having a second width, the second width being wider than the first width; and  
a third lower portion having a third width, the third width being narrower than the second width.

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U.S. Serial No.: Not yet assigned


REMARKS

The amendments to the claims are made to clarify the description. No new matter is added to the application.

Attached hereto is a marked-up version of the changes made to the application by the current Amendment. The attached page is captioned "Version with Markings to Show Changes Made."

Respectfully submitted,

Date: June 12, 2001  
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Version with Markings to Show Changes Made

In the Claims

Claim 10 has been amended as follows:

10. (Amended) A metal interconnect layer for a semiconductor device, comprising:  
a first upper portion having a first width;

a second middle portion having a second width, the second width being wider  
than the first width; and

a third lower portion having a third width, the third width being narrower [wider]  
than the [first and] second width[s].